

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4477659

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HENKEL US IP LLC	02/27/2015
RECEIVING PARTY DATA	
Name:	HENKEL IP & HOLDING GMBH
Street Address:	HENKELSTRASSE 67
City:	DUESSELDORF
State/Country:	GERMANY
Postal Code:	40589
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15426214
CORRESPONDENCE DATA	
Fax Number:	(860)571-5028
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(908) 243-2874
Email:	JOANNE.GUTIERREZ@HENKEL.COM
Correspondent Name:	HENKEL CORPORATION
Address Line 1:	ONE HENKEL WAY
Address Line 4:	ROCKY HILL, CONNECTICUT 06067
ATTORNEY DOCKET NUMBER:	PT032577US
NAME OF SUBMITTER:	JOANNE GUTIERREZ
SIGNATURE:	/JOANNE GUTIERREZ/
DATE SIGNED:	06/26/2017
Total Attachments: 14	
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CONFIRMATORY ASSIGNMENT – UNITED STATES OF AMERICA

WHEREAS,

HENKEL US IP LLC of One Henkel Way, Rocky Hill, CT, 06067, United States of America; (the "Assignor"),

was the owner of inventions in the United States of America set forth and described in the attached Exhibit and forming a part of this document (the "Inventions")

AND WHEREAS,

HENKEL IP & HOLDING GMBH of Henkelstraße 67, 40589 Düsseldorf, Germany (the "Assignee"),

had acquired the entire right, title, interest, property and benefit in and for the United States of America, in and to the Inventions held by the Assignor;

NOW THEREFORE, for good and valuable consideration already provided, the receipt and sufficiency of which are hereby acknowledged,

the Assignor confirms by these presents that the Assignor had assigned, transferred and set over to the Assignee, and to the Assignee's successors, assigns, nominees or other legal representatives, its entire right, title, interest, property and benefit including any right to sue for past infringements in and for the United States of America, in and to the Inventions, any and all applications filed therefor, including any and all corresponding applications whether in the form of divisions, continuations, re-examinations, re-issues and extensions thereof, any and all patents that may issue, be granted or result therefrom for the Inventions, and any and all rights of priority resulting from the filing of any of the above-identified applications and any previously filed applications in respect of the Inventions under international conventions, treaties or otherwise, the same to be held and enjoyed as fully and exclusively as the same would have been held and enjoyed by the Assignor had this assignment not been made;

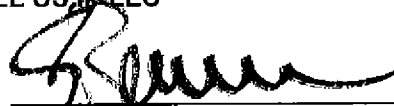
the Assignor agrees to do all lawful acts and to execute and deliver, without further consideration, all further documents as may reasonably be required by the Assignee, or by its successors, assigns, nominees, or other legal representatives, to obtain said patents in the United States of America for the Inventions and vests or secures the same in the Assignee, and in the Assignee's successors, assigns, nominees or other legal representatives; and

the Assignor grants to said Assignee, its successors, assigns, nominees or other legal representatives, agents, the power to insert on this Confirmatory Assignment any further information which may be necessary or desirable in order to legally record this document.

THIS CONFIRMATORY ASSIGNMENT may be executed in counterparts, all of which shall be considered one and the same agreement, and is binding on the heirs, executors, successors and administrators of the Assignor.

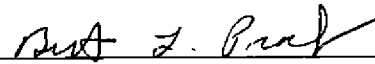
HENKEL US, IP, LLC

By




Name: Steven C. Bauman
Title: Senior Patent Counsel

Subscribed and sworn
before me this 27th day
of February, 2015



Notary Public

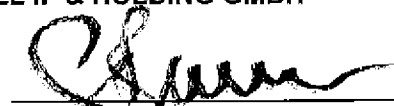
Date:



BETTY L. PROULX
NOTARY PUBLIC
MY COMMISSION EXPIRES _____


HENKEL IP & HOLDING GMBH

By



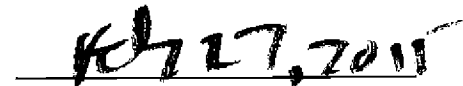
Name: Steven C. Bauman
Title: Senior Patent Counsel

Subscribed and sworn
before me this 27th day
of February, 2015



Notary Public

Date:



BETTY L. PROULX
NOTARY PUBLIC
MY COMMISSION EXPIRES _____

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT031448		US	14-Jan-2014	61/927306			Reactive hot melt adhesives with improved adhesion
2	PT031448		WO	15-Dec-2014	PCT/US2014/070256			Reactive hot melt adhesives with improved adhesion
3	PT032261		US	21-Apr-2014	61/982069			Radiation curable pressure sensitive adhesive
4	PT032391		US	1-May-2014	61/987201			Blocked Acids as Curing Agents for Anaerobic Compositions
5	PT032282		US	6-May-2014	61/988937			Method of applying plural fluids using jet applicators
6	PT032407		WO	24-Jun-2014	PCT/CN2014/080578			UV And Thermal Cure High Temperature Debondable Adhesive
7	PT031905		US	27-Jun-2014	62/018046			Synthetic Method for the Preparation of Acrylic Polymers Terminated with Alkoxysilane Groups
8	PT032566		WO	17-Jul-2014	PCT/CN2014/082388			Photo-curable adhesive composition and use therefor in optical displays
9	PT032208		US	23-Jul-2014	62/027826			Expandable Waterborne Coating Formulation For Padded Envelopes
10	PT032459		US	30-Jul-2014	62/030932			Use of N-Alkanoyl Tetrahydroquinoline and Indoline Derivatives as Anaerobic Adhesive Curatives
11	PT032350		EP	11-Aug-2014	14180538.2			One Pot Synthesis Of Shell Functionalized Nanocrystals And Their Embedment In A Polymer Matrix
12	PT032510		EP	11-Aug-2014	14180543.2			Direct Crosslinking Of Functionalized Nanocrystals Towards Composites
13	PT032577		US	11-Aug-2014	62/035654			Optical clear hot melt adhesive for electronic devices
14	PT032666		EP	11-Aug-2014	14180542.4			Self-Crosslinking of Functionalized Nanocrystals For Optoelectronic Applications
15	PT032757		US	25-Aug-2014	62/041286			Acrylic polymer useful for transdermal drug delivery
16	PT032051		WO	29-Aug-2014	PCT/CN2014/085538			Silicone modified photoinitiator for free radical photocure
17	PT032621		US	5-Sep-2014	62/046317			Hotmelt adhesive Compositions and Use Thereof

PATENT

REEL: 042816 FRAME: 0213

	A	B	C	E	F	G	H	I
	Case Reference - Ref	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT032578		US	16-Sep-2014	62/050979			Use of Hollow Polymeric Microspheres in Composite Materials Requiring Flame Resistance
19	PT032736		US	1-Oct-2014	62/058201			Aromatic Amines with Captodative Substituents on the Nitrogen Atom as Anaerobic Adhesive Curatives
20	PT032646		US	8-Oct-2014	62/061389			Blocked Acids as Curing Agents for Anaerobic Compositions
21	PT032766		WO	9-Oct-2014	PCT/CN2014/088194			Resin Composition For Optical Materials
22	PT032833		US	22-Oct-2014	62/067027			Phenylhydrazine Derivates with Enhanced Solability for Use as Curatives in Anaerobic Adhesives
23	PT032851		WO	27-Oct-2014	PCT/CN2014/089532			Optical semiconductor device and manufacturing method
24	PT032687		EP	5-Dec-2014	14196535			Micro-Reversible Attachment System
25	PT031879		US	8-Dec-2014	62/088976			Process for Making Branched Reactive Block Polymers
26	PT032588		WO	8-Dec-2014	PCT/CN2014/093259			Nanoparticle Conductive Ink Formulation, Process and Application
27	PT032646		US	8-Dec-2014	62/088952			Anaerobic Curable Compositions Containing Blocked Carboxylic Acid Compounds
28								

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT018550	H 09173	US	12-Feb-2014	14/178466			Optical Transparent Dual Cure Adhesives Composition
2	PT018550	H 09173	CN	11-Feb-2014	201280039230.8			Optical Transparent Dual Cure Adhesives Composition
3	PT018550	H 09173	EP	21-Jan-2014	2742108			Optical Transparent Dual Cure Adhesives Composition
4	PT018550	H 09173	JP	10-Feb-2014	2014-524260			Optical Transparent Dual Cure Adhesives Composition
5	PT018550	H 09173	KR	12-Mar-2014	10-2014-7006578			Optical Transparent Dual Cure Adhesives Composition
6	PT018550	H 09173	WO	9-Aug-2012	PCT/CN212/079869			Optical Transparent Dual Cure Adhesives Composition
7	PT018550	H 09173	CN	11-Aug-2011	CN201110230724.1			Optical Transparent Dual Cure Adhesives Composition
8	PT018550	H 09173	TW	4-Jul-2012	101123978			Optical Transparent Dual Cure Adhesives Composition
9	PT018579	H 09205	WO	30-May-2013	PCT/CN2013/176469			Triply Curable Optically Clear Adhesive
10	PT018579	H 09205	US	1-Dec-2014	14/556757			Triply Curable Optically Clear Adhesive
11	PT019015	H 09380	JP	27-Dec-2010	2010-290636			A Hotmelt Adhesive
12	PT019025	H 09386	US	20-Jun-2014	14/309915			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
13	PT019025	H 09386	CN	28-Dec-2012	PCT/CN2012/087801			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
14	PT019025	H 09386	EP	10-Jun-2014	12862543.1			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
15	PT019025	H 09386	JP	27-Jun-2014	2014-549343			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
16	PT019025	H 09386	CN	30-Dec-2011	CN201110459522.4			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
17	PT019025	H 09386	CA	30-Jun-2014	2862440			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
18	PT019025	H 09386	WO	28-Dec-2002	PCT/CN2012/087801			Temporary Bonding Adhesive For Preparation Of Silicon Wafer
19	PT019130		US	23-Jan-2014	14/162288			Photocurable Adhesive Composition and Use Of The Same

PATENT

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT019130		CN	25-Jul-2011	20110211108			Photocurable Adhesive Composition and Use Of The Same
21	PT019130		CN	21-Jan-2014	201280036197.3			Photocurable Adhesive Composition and Use Of The Same
22	PT019130		EP	29-Jan-2014	12818272.2			Photocurable Adhesive Composition and Use Of The Same
23	PT019130		JP	24-Jan-2014	2014-521918			Photocurable Adhesive Composition and Use Of The Same
24	PT019130		KR	24-Jan-2014	2014-7002131			Photocurable Adhesive Composition and Use Of The Same
25	PT019130		TW	22-Jun-2012	101122345			Photocurable Adhesive Composition and Use Of The Same
26	PT019130		WO	5-Jul-2012	PCT/CN2012/078228			Photocurable Adhesive Composition and Use Of The Same
27	PT019222		US	24-Jan-2014	14/162880			Temperature Bonding In For Image Display Applications
28	PT019222		CN	22-Jan-2014	2012800363381.1			Temperature Bonding In For Image Display Applications
29	PT019222		EP	8-Jan-2014	12817262.4			Temperature Bonding In For Image Display Applications
30	PT019222		JP	24-Jan-2014	2014-521923			Temperature Bonding In For Image Display Applications
31	PT019222		KR	16-Jan-2014	PCT/CN2012/078807			Temperature Bonding In For Image Display Applications
32	PT019222		WO	18-Jul-2012	PCT/CN2012/078807			Temperature Bonding In For Image Display Applications
33	PT019222		CN	25-Jul-2011	201110211078.4			Temperature Bonding In For Image Display Applications
34	PT019222		TW	27-Jun-2012	101122923			Temperature Bonding In For Image Display Applications
35	PT019256		US	17-Sep-2014	14/488824			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
36								

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1	PT019256		CA	22-Oct-2014	PCT/US2013/033637			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
37	PT019256		CN	27-Oct-2014	201380022172.2			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
38	PT019256		EP	22-Oct-2014	13780597.4			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
39	PT019256		IN	21-Oct-2014	PCT/US2013/033637			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
40	PT019256		JP	24-Oct-2014	PCT/US2013/033637			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
41	PT019256		KR	24-Nov-2014	10-2014-7032840			Curable Adhesive And Sealant Compositions Comprising Grafted Telechelic Polyisobutylenes Containing Reactive Functionality
42	PT019292		US	26-Feb-2013	13/777337	4-Nov-2014	8877868	Hot Melt Adhesive Comprising Cyanoacrylate Curing Compounds
43	PT019292		WO	18-Feb-2014	PCT/EP2014/053062			Hot Melt Adhesive Comprising Cyanoacrylate Curing Compounds
44	PT019417		WO	10-Jul-2014	PCT/US2014/046074			Polyurethane Adhesives with Improved Barrier Properties
45	PT019562		US	9-Sep-2014	14/481144			Thermally Insulative Compositions And Electronic Devices Assembled Therewith
46	PT019562		CN	14-Nov-2014	201380025192.5			Thermally Insulative Compositions And Electronic Devices Assembled Therewith
47	PT019562		EP	28-Mar-2014	13791522.9			Thermally Insulative Compositions And Electronic Devices Assembled Therewith

PATENT

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	A	B	C	E	F	G	H	I
1	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
49	PT019562		KR	12-Nov-2014	10-2014-70131738			Thermally Insulative Compositions And Electronic Devices Assembled Therewith
50	PT024580	LC-495	US			29-Aug-06	7098279	Non-Flammable And Non-Combustible Adhesive Bonding Systems Having Adherence To Low Energy Surfaces
51	PT027582	N-3342	US	24-Feb-2014	14/188167			
52	PT027696	LDEI-181	US	1-May-2014	14/267579			Method of Spreading Heat And Reducing The Skin Temperature of Electronic Devices
53	PT027696	LDEI-181	EP	28-Mar-2014	12848884.8			Method of Spreading Heat And Reducing The Skin Temperature of Electronic Devices
54	PT027696	LDEI-181	JP	14-May-2014	2014-542359			Method of Spreading Heat And Reducing The Skin Temperature of Electronic Devices
55	PT027696	LDEI-181	KR	12-May-2014	10-2014-7012705			Method of Spreading Heat And Reducing The Skin Temperature of Electronic Devices
56	PT027696	LDEI-181	CN	15-May-2014	201280056138.2			Method of Spreading Heat And Reducing The Skin Temperature of Electronic Devices
57	PT027706	H 08304	KR	18-Jun-2011	10-2011-7016493			Photo-Curable Resin Composition for Ultraviolet Lig
58	PT027805	H 09001	JP	30-Mar-2010	2010-078560			An adhesive for a roll-shaped paper and a roll-shaped paper
59	PT027934	LDEI-159	US	6-Mar-2014	14/199179			Crosslinked Cyanoacrylate Polymer As Solder Powder Coating Materials
60	PT027934	LDEI-159	CN	5-Mar-2014	201280043078.0			Crosslinked Cyanoacrylate Polymer As Solder Powder Coating Materials
61	PT027934	LDEI-159	EP	21-Mar-2014	12830092.8			Crosslinked Cyanoacrylate Polymer As Solder Powder Coating Materials
62	PT027934	LDEI-159	JP	5-Mar-2014	2014-529724			Crosslinked Cyanoacrylate Polymer As Solder Powder Coating Materials
63	PT027970	LDEI-182	US	1-May-2014	14/267552			Thermally Insulative Compositions
64	PT027970	LDEI-182	CN	15-May-2014	201280056366.X			Thermally Insulative Compositions
65	PT027970	LDEI-182	EP	28-Feb-2014	12850645.8			Thermally Insulative Compositions
66	PT027970	LDEI-182	JP	14-May-2014	PCT/US212/064396			Thermally Insulative Compositions

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	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT027970	LDEI-182	KR	30-May-2014	10-2014-7014729			Thermally Insulative Compositions
67	PT027970	LDEI-182	KR	30-May-2014	10-2014-7014621			Thermally Insulative Compositions
68	PT027998	LC-684	US	3-Feb-2014	14/170829			Electrical Conductive Composition of Toughened and Fast Heat and/or Room Temperature Cure For Structural Bonding Applications
69	PT027998	LC-684	EP	12-Feb-2014	12819629.2			Electrical Conductive Composition of Toughened and Fast Heat and/or Room Temperature Cure For Structural Bonding Applications
70	PT027998	LC-684	JP	15-Jun-2014	2014-523928			Electrical Conductive Composition of Toughened and Fast Heat and/or Room Temperature Cure For Structural Bonding Applications
71	PT027998	LC-684	KR	26-Feb-2014	10-2014-7005012			Electrical Conductive Composition of Toughened and Fast Heat and/or Room Temperature Cure For Structural Bonding Applications
72	PT027998	LC-684	CN	27-Jan-2014	201280037533.6			Electrical Conductive Composition of Toughened and Fast Heat and/or Room Temperature Cure For Structural Bonding Applications
73	PT028000	LDEI-194	JP	8-Mar-2012	2014-547184			Selected Coating For Conductive Fillers
74	PT028000	LDEI-194	US	16-Jun-2014	14/305053			Selected Coating For Conductive Fillers
75	PT028031	LC-686	US	1-May-2014	14/266971			Adhesive Composition
76	PT028031	LC-686	CN	14-May-2014	201280055798.9			Adhesive Composition
77	PT028031	LC-686	KR	14-May-2014	10-2014-7013606			Adhesive Composition
78	PT031098	LDEI-185	TW	24-Jan-2014	103102785			Wafer Back Side Coating As Dicing Tape Adhesive
79	PT031231		TW	18-Jul-2013	10212580			Reactive Hot Melt Adhesives
80	PT031248		TW	16-May-2013	102117432			Thermoplastic Film For Packaging Olefin Hot Melt Adhesives
81	PT031266	LC-688	WO	15-Jan-2013	PCT/US2013/21511			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
82								

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT031266	LC-688	US	17-Jul-2014	14/333952			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
83	PT031266	LC-688	EP	1-Jan-2014	13741328.2			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
84	PT031266	LC-688	JP	24-Jul-2014	2014-554736			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
85	PT031266	LC-688	KR	5-Aug-2014	10-2014-7021889			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
86	PT031266	LC-688	CN	25-Jul-2014	201380006873.7			Cyanoacrylate Adhesive Compositions Having Enhanced Humidity And Thermal Resistance
87	PT031327		TW	24-May-2013	1021118481			Process And Methods For Preparing Flow-able Pellets Of Olefin Adhesives With Low Crystallinity
88	PT031328		WO	22-May-2012	PCT/CN2012/075894			Process for Binding Substrates With A Liquid Optically Clear Photo-Curable Adhesive
89	PT031328		TW	15-May-2013	102117157			Process for Binding Substrates With A Liquid Optically Clear Photo-Curable Adhesive
90	PT031344		WO	22-Jul-2013	PCT/CN2013/079762			Phenoxy-Epoxy-Acrylate Hybrid Resin-Platform For Skiv Cure WBC
91	PT031344		TW	1-Jul-2014	103124968			Phenoxy-Epoxy-Acrylate Hybrid Resin-Platform For Skiv Cure WBC
92	PT031392		WO	20-Aug-2012	PCT/CN2012/080359			Liquid Optically Clear Photo-Curable Adhesive For Display Applications
93	PT031392		TW	14-Aug-2013	102129083			Liquid Optically Clear Photo-Curable Adhesive For Display Applications
94	PT031396		WO	22-May-2012	PCT/CN2012/075890			Liquid Optically Clear Photo-Curable Adhesive
95	PT031396		TW	17-May-2013	102117471			Liquid Optically Clear Photo-Curable Adhesive
96	PT031397		TW	29-Apr-2013	102115307			Curable Encapsulants And Use Thereof
97	PT031397		TW	29-Apr-2013	102115307			Curable Encapsulants And Use Thereof

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	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT031409		WO	16-Dec-2013	PCT/US2013/075323			Process of Controlled Radical Polymerization of Branched Polyacrylates
98	PT031411		WO	23-Oct-2013	PCT/US2013/066296			Hot Melt For Overmolding Applications II
100	PT031411		TW	1-Nov-2013	102139848			Hot Melt For Overmolding Applications II
101	PT031428		WO	3-Jul-2013	PCT/CN2013/078759			High Temperature Depondable Adhesive
102	PT031428		TW	3-Jul-2014	103123040			High Temperature Depondable Adhesive
103	PT031481		WO	5-Dec-2012	PCT/CN2012/085935			Silicone Compatible Photoinitiator For Free Radical Photocure
104	PT031481		TW	4-Dec-2013	102144319			Silicone Compatible Photoinitiators
105	PT031487		WO	25-Feb-2014	PCT/US2014/018187			Methods and Apparatus For Controlled Single Electron Transfer Living Radical Polymerization
106	PT031516		TW	10-Mar-2014	103108233			Electronic Devices Assembled With Heat Absorbing and/or Thermally Insulating Composition
107	PT031516		WO	14-Mar-2014	PCT/US2014/027031			Electronic Devices Assembled With Heat Absorbing and/or Thermally Insulating Composition
108	PT031535		WO	26-Jun-2012	PCT/US2012/057267			Oxetane-Containing Compounds And Compositions Thereof
109	PT031535		TW	28-Sep-2012	101136021			Oxetane-Containing Compounds And Compositions Thereof
110	PT031535		US	28-Mar-2014	14/228348			Oxetane-Containing Compounds And Compositions Thereof
111	PT031535		JP	2-Apr-2014	2014-533673			Oxetane-Containing Compounds And Compositions Thereof
112	PT031535		KR	18-Apr-2014	10-2014-7010380			Oxetane-Containing Compounds And Compositions Thereof
113	PT031535		EP	22-Apr-2014	12836054.2			Oxetane-Containing Compounds And Compositions Thereof
114	PT031535		CN	27-May-2014	20128005822.80			Oxetane-Containing Compounds And Compositions Thereof
115	PT031555		US	15-Mar-2013	13/839785			Anaerobic Curable Composition

PATENT

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT031607		US	30-Sep-2013	61/884844			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
116	PT031607		TW	18-Jul-2014	103125744			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
117	PT031607		WO	29-Sep-2014	PCT/US2014/058000			Conductive Die Attach Film for Large Die Semiconductor Packages and Compositions Useful for the Preparation Thereof
118	PT031610		WO	23-Jan-2013	PCT/CN2013/070873			UV/Heat Curable Underfill Adhesive And Its Application Method
119	PT031610		TW	23-Jan-2014	103102529			UV/Heat Curable Underfill Adhesive And Its Application Method
120	PT031617		TW	12-Mar-2014	103108808			Oxetane-Containing Compounds And Compositions Thereof
121	PT031617		WO	18-Mar-2014	PCT/US2014/027458			Oxetane-Containing Compounds And Compositions Thereof
122	PT031646		TW	23-Jan-2014	103102527			Flexible Conductive Ink
123	PT031649		WO	22-Oct-2013	PCT/US2013/066063			Adhesive Composition
124	PT031649		TW	25-Oct-2013	102138758			Adhesive Composition
125	PT031661		TW	18-Mar-2014	103110177			Diene/Dienophile Couples And Thermosetting Resin Compositions Having Reworkability
126	PT031661		WO	21-Mar-2014	PCT/US2014/031453			Diene/Dienophile Couples And Thermosetting Resin Compositions Having Reworkability
127	PT031681		WO	28-May-2014	PCT/US2014/039693			Primer Compositions For Injection Molding
128	PT031755		US	15-Dec-2014	14/570060			Photocrosslinkable Block Copolymers For Hot-Melt Adhesives
129	PT031844		WO	22-May-2014	PCT/US2014/039138			Tri-Layer Adhesive For The Encapsulation of Electronic Devices
130	PT031844		WO	23-May-2014	103118133			Tri-Layer Adhesive For The Encapsulation of Electronic Devices
131	PT031844		TW	23-May-2014	103118133			Tri-Layer Adhesive For The Encapsulation of Electronic Devices

PATENT

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1								
132	PT031884		WO	9-Jul-2014	PCT/US2014/045862			Sintering Films For Bonding Applications
133	PT031884		TW	25-Jul-2014	103125600			Sintering Films For Bonding Applications
134	PT031924		WO	9-May-2014	PCT/US2014/037476			Functional Polyisobutylene-Containing Oligomers and Polymers
135	PT031924		TW	9-May-2014	103116613			Functional Polyisobutylene-Containing Oligomers and Polymers
136	PT031960		TW	30-Jun-2014	103122570			Nanoparticle Ink Compositions, Process and Application
137	PT031960		WO	1-Jul-2014	PCT/US2014/044990			Nanoparticle Ink Compositions, Process and Application
138	PT031961		US	16-Aug-2013	61/866825			Sub-Micron Silver Particle Ink Composition, Process and Application
139	PT031961		WO	8-Jul-2014	PCT/US2014/045729			Sub-Micron Silver Particle Ink Composition, Process and Application
140	PT031961		TW	9-Jul-2014	103123700			Sub-Micron Silver Particle Ink Composition, Process and Application
141	PT031985		WO	22-Aug-2013	PCT/CN2013/082081			High Molecular Weight Polymers Having High Olefin Content
142	PT031985		TW	25-Aug-2014	103129211			High Molecular Weight Polymers Having High Olefin Content
143	PT031986		TW	21-Jul-2014	103124995			Methods To Control Wafer Warpage Upon Compression Molding Thereof And Articles Useful Therefor
144	PT031986		WO	8-Jul-2014	PCT/US2014/045710			Methods To Control Wafer Warpage Upon Compression Molding Thereof And Articles Useful Therefor
145	PT032168		TW	25-Jul-2014	103125599			Compositions Having A Matrix And Encapsulated Phase Change Materials Dispersed Therein, and Electronic Devices Assembled Therewith
146	PT032168		WO	15-Dec-2014	PCT/US2014/070462			Compositions Having A Matrix And Encapsulated Phase Change Materials Dispersed Therein, and Electronic Devices Assembled Therewith

	A	B	C	E	F	G	H	I
	Case Reference	Original Ref	CTY	Filing Date	Appl No.	Grant Date	Grant No.	Internal Title
1	PT032168		US	19-Dec-2013	61/918358			Compositions Having A Matrix And Encapsulated Phase Change Materials Dispersed Therein, and Electronic Devices Assembled Therewith.
147								